



MFF2 Packaging specifications

v1.1

25-Jan-2019

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1 Introduction

The ConnectedYou SIM allows a user to download & delete Connectivity Provider profiles on the SIM Over-The-Air. This decouples the SIM hardware from connectivity the Connectivity Provider provides giving the user the benefit of always being in control of their connectivity ecosystem.

The ConnectedYou SIM is built using standard & industry approved eUICC functionality to manage Connectivity Providers on the SIM with GSMA endorsed security guidelines.

The ConnectedYou SIM is available in 3 Form Factors:



Plug-in (2FF+3FF+4FF)



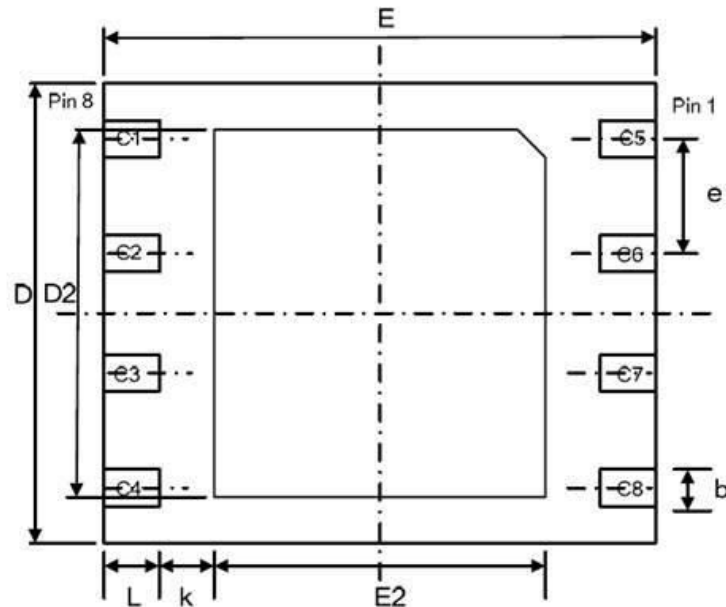
MFF2



WLCSP & DFN6

This document provides technical specifications for ConnectedYou MFF2 (embedded SIM/ eSIM) products.

2 VQFN8/ MFF2 Packaging footprint

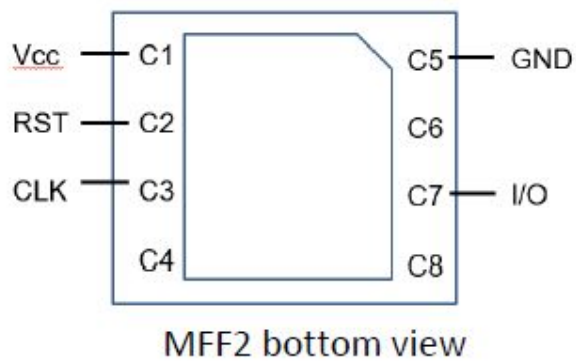


MFF2 bottom view

Parameter	Description	Dimensions (mm)
E	The package body dimension in the horizontal direction.	6,00 ± 0,15
D	The package body dimension in the vertical direction.	5,00 ± 0,15
L	The length of the contact as measured from the edge of the package.	0,60 ± 0,15
b	The width of the metallised contacts (including lead finish) exposed at the bottom surface of the package.	0,40 ± 0,10
E2	The horizontal dimension of the exposed metal heat feature (exposed die pad).	min 3,30
D2	The vertical dimension of the exposed metal heat feature (exposed die pad).	min 3,90
k	The gap between any contact and the heat feature.	min 0,20
e	The centreline-to-centreline spacing of the contacts.	1,27 for tolerances see parameters bbb and ddd
bbb	The tolerance that controls the position of the contact pattern with respect to the horizontal package centreline. The centre of the tolerance zone for each contact is defined by basic dimension e as related to the horizontal package centreline.	0,10
ddd	The tolerance that controls the position of the contacts to each other. The centres of the profile zones are defined by basic dimension e.	0,05

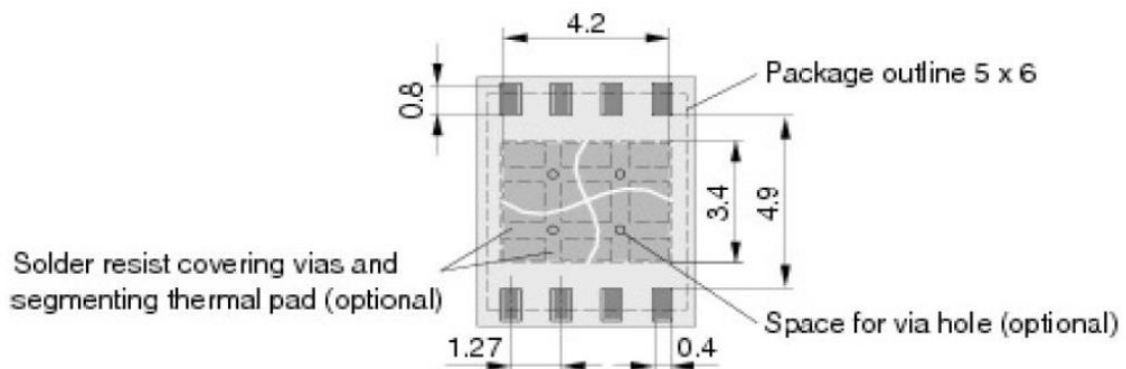
Dimensions of MFF2

3 Pinout Configuration (ETSI TS 102 221)



C1	Vcc
C2	RST
C3	CLK
C4	-
C5	GND
C6	-
C7	I/O
C8	-

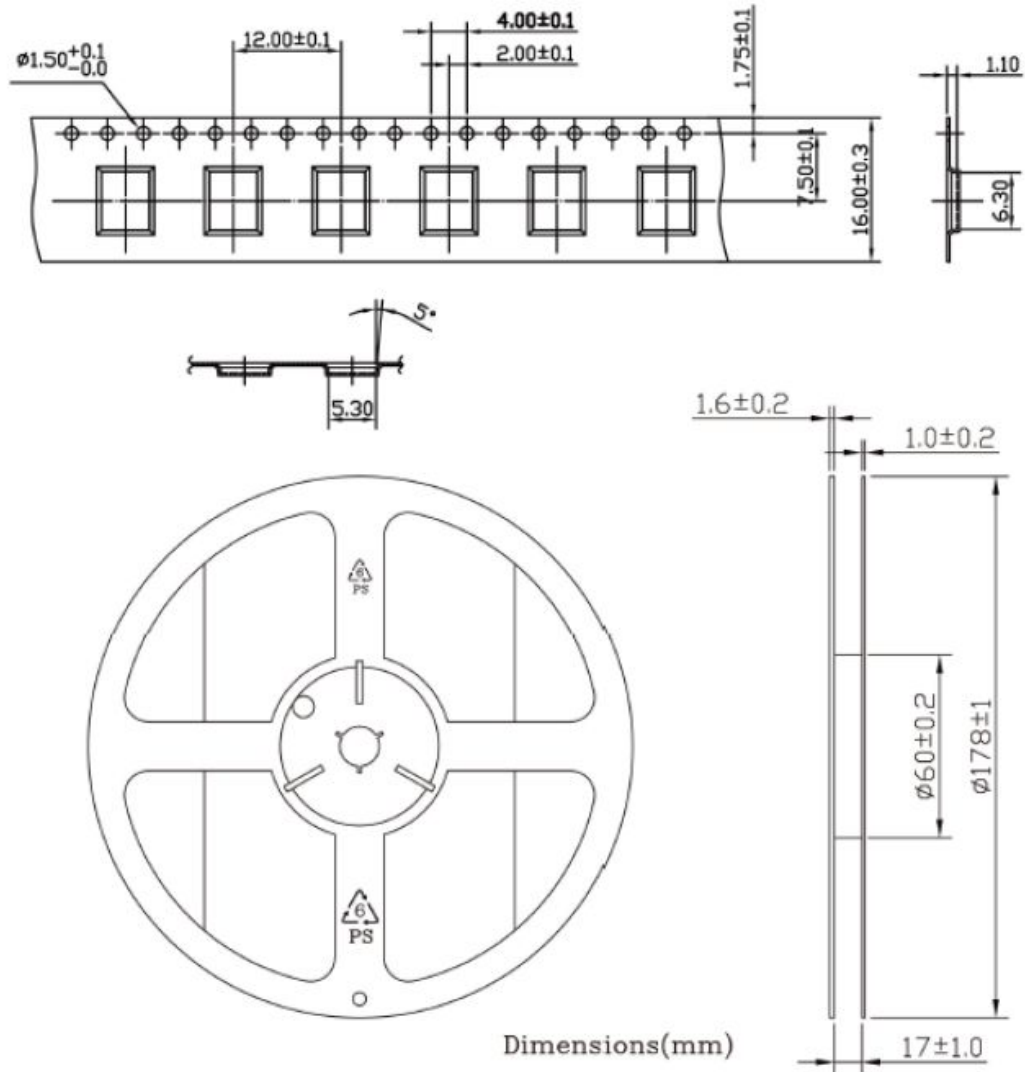
4 Recommendation for PCB Footprint



6 Packaging Tape & Reel Dimension

MFF2 products come in a reel of minimum 1,000 pcs encased in a container depicted below. It is possible that a lesser number is shipped outside of the container if a lower quantity is requested.

The dimensions of the reel and the container are shown below as references.



Reel and container dimensions

Revision History

Version	Date	Remarks
1.0	18-Jun-2018	Initial version
1.1	25-Jan-2019	Amended Packing specifications for MFF2